

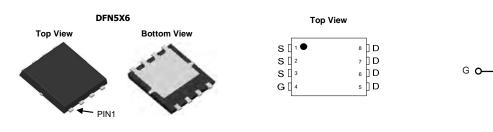
# NCEP60T15G-VB Datasheet N-Channel 60 V (D-S) MOSFET

PRODUCT SUMMARY							
V <sub>DS</sub> (V)	V <sub>DS</sub> (V) R <sub>DS(on)</sub> (Ω)						
60	0.003 at V <sub>GS</sub> = 10 V	100					
00	0.005 at V <sub>GS</sub> = 4.5 V	85					

### **FEATURES**

- 175 °C Junction Temperature
- Trench Power MOSFET
- Material categorization:





S N-Channel MOSFET

D

ABSOLUTE MAXIMUM RATINGS (T <sub>C</sub> = 25 °C, unless otherwise noted)						
Parameter	Symbol	Limit	Unit			
Gate-Source Voltage	V <sub>GS</sub>	± 20	V			
Continuous Drain Current (T <sub>.1</sub> = 175 °C) <sup>b</sup>	T <sub>C</sub> = 25 °C	1-	100			
Continuous Drain Current $(T_J = 175 \text{ °C})^2$	T <sub>C</sub> = 100 °C	I <sub>D</sub>	85 <sup>a</sup>			
Pulsed Drain Current	I <sub>DM</sub>	100	А			
Continuous Source Current (Diode Conduction)	۱ <sub>S</sub>	80 <sup>a</sup>				
Avalanche Current	I <sub>AS</sub>	70				
Single Avalanche Energy (Duty Cycle $\leq$ 1 %)	L = 0.1 mH	E <sub>AS</sub>	125	mJ		
Movimum Dower Discipation	T <sub>C</sub> = 25 °C	P <sub>D</sub>	136	w		
Maximum Power Dissipation	T <sub>A</sub> = 25 °C		3 <sup>b</sup> , 8.3 <sup>b, c</sup>	vv		
Operating Junction and Storage Temperature Range	T <sub>J</sub> , T <sub>stg</sub>	- 55 to 175	°C			

THERMAL RESISTANCE RATINGS							
Parameter		Symbol	Typical	Maximum	Unit		
Manimum lugation to Amhienta	t ≤ 10 sec	R <sub>thJA</sub>	15	18	°C/W		
Maximum Junction-to-Ambient <sup>a</sup>	Steady State		40	50			
Maximum Junction-to-Case	R <sub>thJC</sub>	0.85	1.1				
Notes:							

a. Package limited.

c. t  $\leq$  10 s.

b. Surface mounted on 1" x 1" FR4 board.

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Parameter	Symbol	Test Conditions	Min.	Typ. <sup>a</sup>	Max.	Unit	
Static			1		<u> </u>		
Drain-Source Breakdown Voltage	V <sub>DS</sub>	$V_{GS} = 0 V, I_D = 250 \mu A$	60			V	
Gate Threshold Voltage	V <sub>GS(th)</sub>	$V_{DS} = V_{GS}, I_D = 250 \ \mu A$	1	2	3	v	
Gate-Body Leakage	I <sub>GSS</sub>	$V_{DS} = 0 V, V_{GS} = \pm 20 V$			± 100	nA	
		V <sub>DS</sub> = 60 V, V <sub>GS</sub> = 0 V	1		1		
Zero Gate Voltage Drain Current	I <sub>DSS</sub>	$V_{DS} = 60 \text{ V}, \text{ V}_{GS} = 0 \text{ V}, \text{ T}_{J} = 125 \text{ °C}$			50	μA	
		$V_{DS} = 60 \text{ V}, \text{ V}_{GS} = 0 \text{ V}, \text{ T}_{J} = 175 \text{ °C}$			250		
On-State Drain Current <sup>b</sup>	I <sub>D(on)</sub>	$V_{DS} = 5 V, V_{GS} = 10 V$	60			Α	
		V <sub>GS</sub> = 10 V, I <sub>D</sub> = 20 A		0.003		Ω	
	Б	V <sub>GS</sub> = 10 V, I <sub>D</sub> = 20 A, T <sub>J</sub> = 125 °C		0.008			
Drain-Source On-State Resistance <sup>b</sup>	R <sub>DS(on)</sub>	V <sub>GS</sub> = 10 V, I <sub>D</sub> = 20 A, T <sub>J</sub> = 175 °C		0.010			
		V <sub>GS</sub> = 4.5 V, I <sub>D</sub> = 15 A		0.005			
Forward Transconductance <sup>b</sup>	9 <sub>fs</sub>	V <sub>DS</sub> = 15 V, I <sub>D</sub> = 20 A		60		S	
Dynamic							
Input Capacitance	C <sub>iss</sub>			2650		pF	
Output Capacitance	C <sub>oss</sub>	$V_{GS}$ = 0 V, $V_{DS}$ = 25 V, f = 1 MHz		470			
Reverse Transfer Capacitance	C <sub>rss</sub>			225			
Total Gate Charge <sup>c</sup>	Qg			47	70		
Gate-Source Charge <sup>c</sup>	Q <sub>gs</sub>	$V_{DS} = 30 \text{ V}, \text{ V}_{GS} = 10 \text{ V}, \text{ I}_{D} = 50 \text{ A}$		10		nC	
Gate-Drain Charge <sup>c</sup>	Q <sub>gd</sub>			12			
Turn-On Delay Time <sup>c</sup>	t <sub>d(on)</sub>			10	20		
Rise Time <sup>c</sup>	t <sub>r</sub>	$V_{DD}$ = 30 V, $R_{L}$ = 0.6 $\Omega$		15	25	- ns	
Turn-Off Delay Time <sup>c</sup>	t <sub>d(off)</sub>	$\text{I}_\text{D}\cong$ 50 A, $\text{V}_\text{GEN}$ = 10 V, $\text{R}_\text{g}$ = 2.5 $\Omega$		35	50		
Fall Time <sup>c</sup>	t <sub>f</sub>			20	30		
Source-Drain Diode Ratings and Cha	aracteristics (	T <sub>C</sub> = 25 °C)		<u> </u>	·		
Pulsed Current	I <sub>SM</sub>				60	А	
Diode Forward Voltage	V <sub>SD</sub>	I <sub>F</sub> = 20 A, V <sub>GS</sub> = 0 V		1	1.5	V	
Dioue i orwaru voltage	• 50	·F =0/., ·GS 0.			1.5	v	

SPECIFICATIONS	(T	= 25 °C, unless otherwise noted)
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Notes:

a. For design aid only; not subject to production testing.

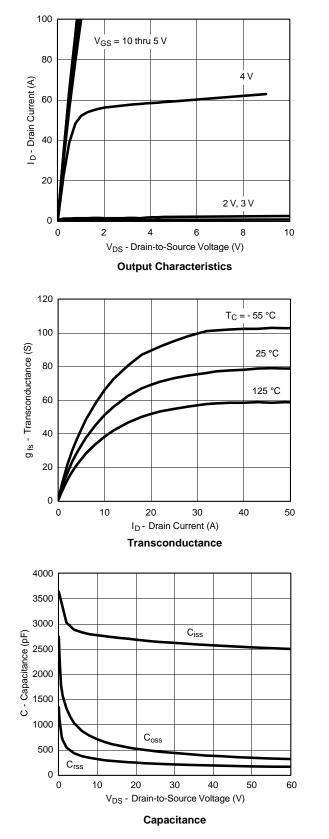
b. Pulse test; pulse width  $\leq$  300 µs, duty cycle  $\leq$  2 %.

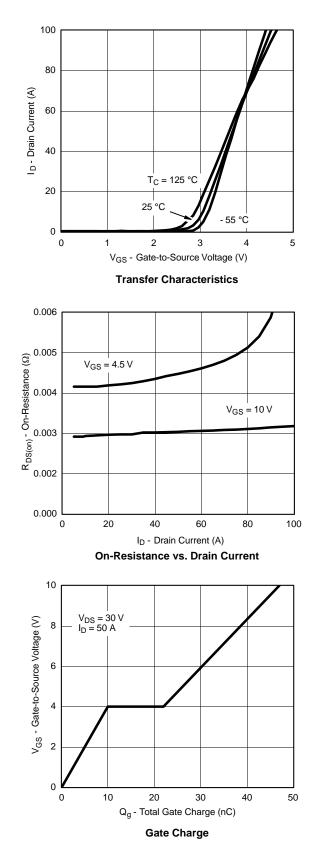
c. Independent of operating temperature.

Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.



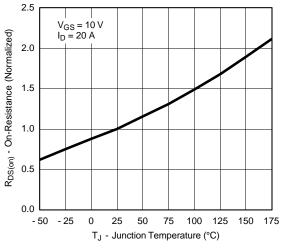
### TYPICAL CHARACTERISTICS (25 °C unless noted)



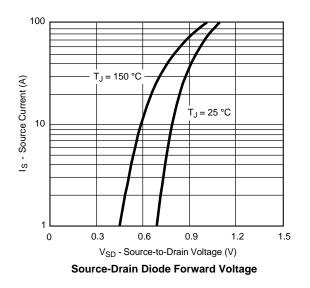




### TYPICAL CHARACTERISTICS (25 °C unless noted)



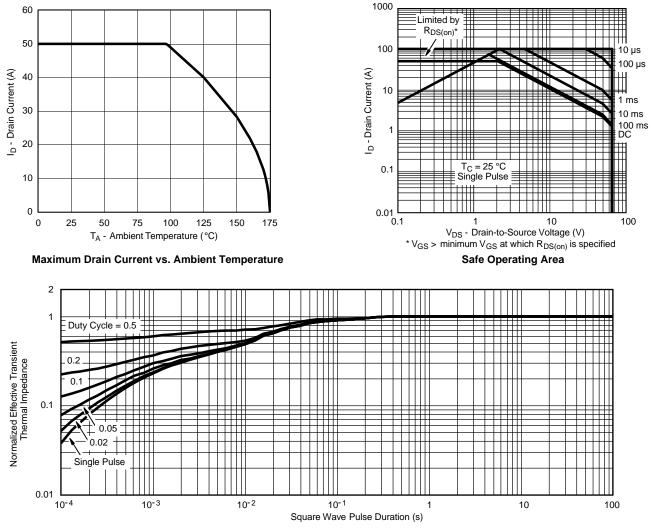
**On-Resistance vs. Junction Temperature** 



### NCEP60T15G-VB

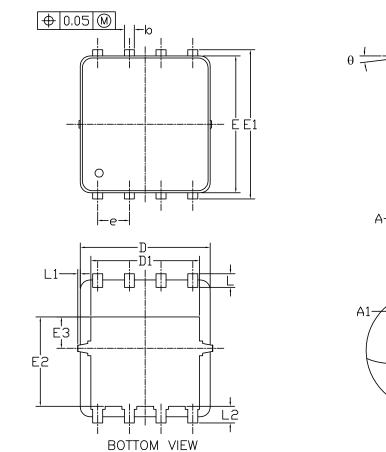


#### **THERMAL RATINGS**



Normalized Thermal Transient Impedance, Junction-to-Case





DFN5x6\_8L\_EP1\_P PACKAGE OUTLIN

A1

С

VIEW 'A'

(SCALE 5:1)

**RECOMMENDED LAND PATTERN** .60 -0.55 0.50 -0.77 -0.635 4.12 6.15 -1.60 + 0.65 +|+| + ŧ -11.27-0.50-

SYMBOLS	DIMENSIONS IN MILLIMETERS			DIMENSIONS IN INCHES			
SIMBOLS	MIN	NOM	MAX	MIN	NOM	MAX	
Α	0.85	0.95	1.00	0.033	0.037	0.039	
A1	0.00		0.05	0.000		0.002	
b	0.30	0.40	0.50	0.012	0.016	0.020	
с	0.15	0.20	0.25	0.006	0.008	0.010	
D	5.10	5.20	5.30	0.201	0.205	0.209	
D1	4.25	4.35	4.45	0.167	0.171	0.175	
Е	5.45	5.55	5.65	0.215	0.219	0.222	
E1	5.95	6.05	6.15	0.234	0.238	0.242	
E2	3.525	3.625	3.725	0.139	0.143	0.147	
E3	1.175	1.275	1.375	0.046	0.050	0.054	
e		1.27 BSC		0.050 BSC			
L	0.45	0.55	0.65	0.018	0.022	0.026	
L1	0		0.15	0		0.006	
L2		0.68 REF			0.027 REF		
θ	0°		10°	0°		10°	

NOTE

UNIT: mm

 PACKAGE BODY SIZES EXCLUDE MOLD FLASH AND GATE BURRS. MOLD FLASH AT THE NON-LEAD SIDES SHOULD BE LESS THAN 6 MILS EACH.
CONTROLLING DIMENSION IS MILLIMETER.

CONVERTED INCH DIMENSIONS ARE NOT NECESSARILY EXACT.



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